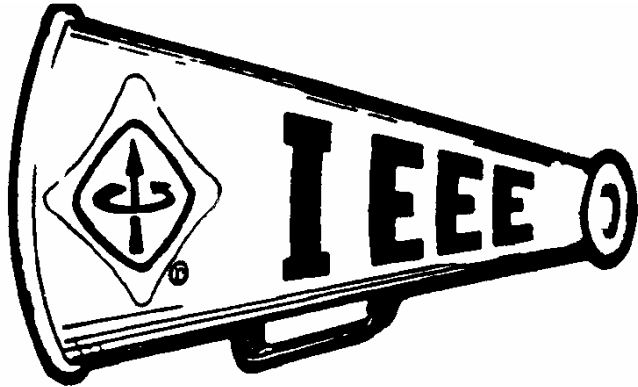


The Valley Megaphone



Newsletter of the
**Institute of Electrical and
Electronics Engineers, Inc.**
Phoenix Section
December 2005, Volume XIX, Number 12

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This Issue of The Valley Megaphone Features:

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IEEE Phoenix Section Executive Committee meeting minutes can be found at: <http://www.ieee.org/phoenix>

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The Valley Megaphone is the newsletter of the Phoenix Section of the Institute of Electrical and Electronics Engineers. It is published monthly and reaches about 4000 members. Submit articles, advertisements, and announcements to Eric Palmer at the above email address. Deadline for announcements and advertisements is the third Friday of the month prior to publication.

Advertising Rates: Full page: \$200, 3/4page: \$125, 1/2 page: \$75, 1/3 page: \$50, 1/4 page: \$25.

Change of address/email? Call toll free 1-800-678-IEEE. Please allow 6-8 weeks. Section Web Page is: <http://www.ieee.org/phoenix>

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Embry-Riddle Computer Society

Advisor:

ECTC 2006

The 56th Electronic Components and Technology Conference

May 30 - June 2, 2006
 Sheraton San Diego Hotel & Marina
 San Diego, California USA

Introduction

It is my pleasure to invite you to submit an abstract for the 56th Electronic Components and Technology Conference (ECTC), to be held May 30 - June 2, 2006 in San Diego, California. This premier international conference is sponsored jointly by the IEEE Components, Packaging and Manufacturing Technology Society (CPMT) and the Electronic Components, Assemblies, and Materials Association (ECA), the electronic components sector of the Electronic Industries Alliance (EIA). You are not required to be a member of either organization to present a paper or attend the conference.

The ECTC comprises papers covering a wide spectrum of topics, including electronic components, materials, assembly, packaging, system packaging, optoelectronics, reliability, and simulation. We have also included a topic on emerging technologies in the program to address exciting new developments and applications. A plenary session and a panel discussion address selected topics each year. Authors from companies, research institutes, and universities located around the world presented more than 300 papers and posters at the 2005 ECTC to about 1,000 conference participants.

Professional Development Courses covering 16 different topics are offered by world-class experts in their fields. Participants can catch up with new technology developments and broaden their technical knowledge base. The technical program and professional development courses are supplemented by the technical exhibition corner. Leading companies primarily in the electronics components, materials, and packaging field exhibit their latest technologies and products.

The ECTC Program Committee represents a wide range of disciplines and expertise from the electronics industry. I would like to encourage you to submit an abstract on your recent, previously unpublished work to the 56th ECTC at www.ectc.net. The deadline for abstract submission is October 15, 2005. I look forward to seeing you in sunny San Diego, California in May 2006.

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For information about past proceedings (printed or CD-ROM), visit the ECTC website www.ectc.net.

Visit the ECTC website (www.ectc.net) for additional conference information.

Major Topics

Papers presenting new developments and knowledge in the following areas are invited. Please select two subcommittees that should consider your paper. The work submitted should be original and not previously published, and avoid the inclusion of commercial content.

- **Advanced Packaging:** New packaging technologies, systems packaging, first level thermal solutions for high power applications, design, materials, and configurations addressing performance, density and cooling for single chip, multichip, wafer-level, MEMS and power packages. Special emphasis on flip-chip, fine pitch and high lead count packaging in CSP, BGA, CGA, LGA and SMT packages for both Pb-based and Pb-free bumps and package assembly.
- **Components & RF:** New passive or active component technologies, integrated-embedded components, RF and wireless component applications, modules with subsystem functionality, component performance, and reliability.
- **Education:** Education for engineering curricula in the 21st century and collaborative research and engineering programs between universities, government, or industry, development and the use of multimedia for packaging education.
- **Emerging Technologies: Biomedical, Nano-Scale and Organic Device Packaging:** Packaging of biomedical and bio-sensing devices, micro-fluidic devices, bio-compatible materials, micro-to-nano transition, nano-electro-mechanical systems (NEMS), organic electronic devices (active and passive), and systems. Materials, fabrication, characterization, optical properties, packaging, and reliability. Applications: nano fluids, optics, and mechanics, RRD, electronic papers, flex circuits, bio-compatibility. See next page for more information.
- **Interconnections:** First-level electronic interconnection technologies including flip-chip, lead-free, fine pitch bump, wafer level and novel interconnection structures and processes, MEMS interconnect, under bump metallurgy, high density (HCD) substrates interconnect, wirebonding, conductive polymers for interconnect, interconnectors for 3D stacking (SPSOP), interconnection for new Silicon technologies (e.g. low-k), thermal, mechanical, and electrical aspects of interconnect structures, electromigration of bumped interconnects.
- **Manufacturing Technology:** Advanced process development and equipment improvement for wafer thinning, bumping, stacking, low-k chip and wire packaging, high-density interconnect and embedded component substrates, testing and burn-in. Emphasis on product level integration and optimization for different product applications, cost, yield, performance and environmental improvements, process characterization, new product introduction and ramp, design for flexible manufacturing and testing.
- **Materials & Processing:** Processes for IC Packaging that enhance performance (mechanical, thermal and electrical) and cost effectiveness. These include new technologies, development and application of adhesive, encapsulants, chip underfills, solders and alloys, magnetic and optical materials, thermal interface materials, ceramics, composites, dielectrics, thin films, nanomaterials to bonding, plating and other assembly processes.
- **Modeling & Simulation:** Electrical, thermal, optical, mechanical modeling, simulation, characterization and packaging solutions including system-level applications.
- **Optoelectronics:** Packaging for fiber-optic modules, optical devices and components including optical amplifiers, lasers, detectors, OBCs, and passive components, non-harmful and plastic optical packages, optoelectronic package manufacturing, materials, fabrication and process technology, solid state lighting (LEDs and display arrays), optical data interconnect, WDMs, fiber-to-the-home, arrays and broad area lasers and optical back-planes.
- **Posters:** Papers may be submitted on any of the listed major topics; presentation of papers in a poster format is highly encouraged at ECTC.
- **Quality & Reliability:** Reliability assessment and prediction at the system, PWB or package level; reliability testing and data analysis; failure analysis of field and test failures; reliability modeling of accelerated testing; reliability issues in emerging technologies; interconnect reliability physics, testing and predictive simulation; advances in reliability test methods and failure analysis.

Professional Development Courses

Proposals are also solicited from individuals interested in teaching educational short courses (4 hours) on topics described in the Call for Papers.

Proposals including course descriptions must be submitted by October 15, 2005 via the website at www.ectc.net. For more information please contact Ridley Lee, phone +852-2358-7203, rlcylee@ust.hk.

Paper Submission

You are invited to submit a 750 word abstract that describes the scope, content, and key points of your proposed paper via the website at www.ectc.net. Please check the website for details on how to submit abstracts electronically. For additional information regarding abstract and paper submissions, please contact torsten@astr1.org.

The abstracts must be received by October 15, 2005. Your submission must include the mailing address, business telephone number and facsimile number, and email address of the presenting author and affiliations of all authors. Please indicate no more than two program subcommittees that should evaluate your paper for acceptance. Authors will be notified of paper acceptance with instructions for publication by December 19, 2005. At the discretion of the program committee, abstracts submitted may be considered for poster sessions.

Manuscripts are due in final form for publication in the Conference Proceedings by February 3, 2006. The work submitted should be original and not previously published, and avoid inclusion of commercial content. In addition to a printed copy conforming to the ECTC format, a computer file for the CD-ROM is needed in the preferred MS Word format.

Special Paper Recognition

Best Paper Award: Each year the ECTC selects the best paper whose author(s) receive an ECTC personalized wall plaque and share a check for \$2500.

Best Poster Award: Each year the ECTC selects the best poster paper whose author(s) receive an ECTC personalized wall plaque and share a check for \$1500.

Outstanding Paper Awards: Other outstanding conference papers are also selected for special recognition by the ECTC. The author(s) receive a personalized wall plaque and share a check for \$1000.

Outstanding Poster Awards: Other outstanding poster papers are also selected for special recognition by the ECTC. The author(s) receive a personalized wall plaque and share a check for \$1000.

Intel Best Student Paper Award: Intel Corporation is sponsoring an award for the best paper submitted and presented by a student at the ECTC. The winning student will be presented with a wall plaque and a check for \$2500.

IEEE CPMT Transactions: In addition to the publication of papers in the Conference Proceedings, a selection of the top papers is published in a special issue of the IEEE CPMT Transactions.

Technology Corner Exhibits

Reserve Your Space Early!

Exhibit your products or services to more than 1,000 engineers and managers from all electronic disciplines including: Packaging, Interconnections, MCMs, Hybrids, Thermal Management, Modeling, Quality, Reliability, Materials, Processing, Components and Optoelectronics. One and one-half days, May 31 & June 1, 2006.

More than 70 percent of the 68 booths available have been reserved by 2005 exhibitors. For information and an application, contact Bill Moody by email: b.o.moody@ieee.org.

Advance Programs will be available February 2006.
Contact Steve Bezuk, Kyocera America Corporation,
8611 Balboa Ave., San Diego, CA 92064.
Phone (858) 576-2651, Fax: (858) 569-9412,
Email: steve.bezuk@kyocera.com.

Emerging Technologies: Biomedical, Nano-Scale Packaging and Organic Device Packaging

As part of the ECTC Program Committee's commitment to provide coverage of advanced and emerging technologies, we are soliciting abstracts for the 2006 ECTC on three special topics: "Biomedical Packaging," "Nano-Scale Packaging," and "Organic Device Packaging." When you submit your abstracts on the ECTC website, www.ectc.net, select "Emerging Technologies" as the primary review committee.

Biomedical packaging is experiencing increased interest as the devices are shrinking and more point-of-care biochips are being developed with integrated capabilities for diagnostics, drug delivery, precision surgery, prosthetics, as well as pathogen and bio-sensing. Platforms that integrate biological processing, transducers, circuits, and communications require special packaging that can handle microfluidic as well as microelectronic and optical systems. The conference is especially interested in presentations describing integration of functionality as well as miniaturization of the devices. Abstracts are being solicited for development of packaging for these devices that cover device design, materials, fabrication methods, and complete packaging of biomedical and other biotechnology systems, especially in regards to miniaturization, integration, biocompatibility, disposable applications, measurement and testing.

Nano-scale technologies are being developed for the next generation of devices. Packaging and interconnect of these nano-scale devices need to be developed, including the nano-to-micro transitions and interfaces. At the same time, nano-scale structures are being developed and are enabling new interconnect methodologies. Abstracts are being solicited for both packaging of nano-devices, such as high-sensitivity gas and biosensors, as well as development of the new generation of materials for interconnect and packaging materials that utilize nanosize structures such as carbon nanotubes and nanowires. The topic is calling for devices, materials, and processes that result in or support submicron size structures. Some specific topics of interest include use of nanowires for interconnect, nanopatterning technologies, NEMS, nanofluidics, and special properties at nano-scale such as nanomagnetism.

Organic device technology is developing rapidly especially for low-cost applications. Similarly, organic LEDs and optoelectronic systems show great promise. Polymers have long been key packaging materials, and organic electronics offer the opportunity to embed active devices with passives, and to merge device and packaging technologies. Papers are sought in all areas of organic device technologies.

14th Motorola-IEEE CPMT Society Graduate Student Fellowship for Research on Electronic Packaging

The IEEE Components, Packaging and Manufacturing Technology Society (CPMT) is pleased to announce a Fellowship for Research on Electronic Packaging sponsored by Motorola, Incorporated.

Description: The purpose of the Fellowship is to promote graduate-level study and research on electronic packaging. An annual award will be made to a student enrolled full-time in a graduate curriculum leading to a Ph.D. and whose major field of interest is in electronic packaging. For the purpose of this award, electronic packaging research is defined as the fundamental study of the design analysis or characterization, construction, manufacturing, or reliability of the electronic interconnection of semiconductor or photonic devices, or the thermal management of mechanical assembly of said devices. All forms of electronic packaging are included from low power to high power, low performance to high performance, including applications ranging from computers, telecommunications, and aerospace to automobiles and manufacturing systems as they relate to electronic packaging.

Eligibility: Candidates must have completed a minimum of four years of college (U.S. and/or non-U.S. colleges, universities or institutes) and a year of graduate study in a recognized engineering or scientific curriculum. They must be enrolled in a doctoral program whose major field of interest is in electronic packaging.

The award will be based on a student paper competition to be conducted in the Electronic Components and Technology Conference (ECTC) which is sponsored jointly by the CPMT Society of the IEEE, and the ECA. Students must submit abstracts to the Program Committee of the ECTC in accordance with the ECTC "Call for Papers" and indicate desire to be considered for the Motorola Fellowship on their abstract.

Travel Support: The IEEE CPMT Society will provide travel reimbursement of up to \$1000 for seven Fellowship finalists, chosen based on submitted manuscripts. Fellowship candidates not chosen as finalists may be provided up to \$500 in travel reimbursement. ECTC conference registration fees will be waived for all seven Fellowship finalists.

For information regarding the Fellowship, please contact Andrew Skipor at aas002@gmail.com.

Nominations Solicited for IEEE CPMT Society Awards

CPMT Society solicits nominations for the following awards for the year 2006. These awards are offered for the purpose of recognizing outstanding service and contributions to furthering the professional purposes of IEEE and CPMT Society. For nomination guidelines, basis of judging, and further information about the awards, please visit the website <http://www.cpmt.org/awards>. Nomination forms can be obtained from the website, or from the CPMT awards committee chair. Minimum **three** reference letters must be submitted in support of all nominations. Reference letters can be provided by IEEE/CPMT members and non-members. **The due date for receiving the nominations is January 31, 2006.**

David Feldman Outstanding Contribution Award: To recognize outstanding contributions to the fields encompassed by the CPMT Society through executive or managerial directions.

Prize: \$2,500 and Certificate

Eligibility: Recipient must have been a member of IEEE and CPMT for the past five (5) years, including 2005.

Outstanding Sustained Technical Contributions Award: To recognize outstanding sustained and continuing contributions to the technology in fields encompassed by the CPMT Society.

Prize: \$2,500 and Certificate

Eligibility: Must have been a member of the IEEE and CPMT Society for the past three (3) years, including 2005.

Electronics Manufacturing Technology Award: To recognize major contributions to Electronic Manufacturing Technology in fields encompassed by the CPMT Society.

Prize: \$2,500 and Certificate

Eligibility: No need to be a member of IEEE and CPMT Society.

Exceptional Technical Achievement Award: To recognize an individual, or group of individuals (no more than three), for exceptional technical achievement in the fields encompassed by the CPMT Society.

Prize: \$2,500 and a Certificate.

Eligibility: Recipient(s) must have been a member of IEEE and CPMT for the past three (3) years, including 2005. There are no requirements for service to the IEEE or CPMT Society.

Outstanding Young Engineer Award: To recognize outstanding contributions to the fields encompassed by the CPMT Society through invention, technical development, publications, or new product implementation.

Prize: \$1,500 and Certificate plus one year free membership in CPMT with all CPMT Transactions.

Eligibility: Must have been a member of the IEEE and CPMT (member grade or above) for the past three (3) years, including 2005, and must be 35 years of age, or younger, on December 31st, 2005.

Please send nominations to CPMT Society Awards Committee Chair by e-mail, fax or mail:

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2100 East Elliot Road,
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Phone: +1-480-413-6121
Fax: +1-480-413-4511
Email address: r.bonda@ieee.org or rao.bonda@freescale.com

Winners will be notified by February 28, 2006 and the awards will be presented at the 56th Electronic Components and Technology Conference, May 30- June 2, 2006, in San Diego, California, USA.

2005 Call for IEEE Phoenix Section Award Nominations

The deadline for receiving your nominations for the year 2005 IEEE Phoenix Section awards is just three weeks away. This is your valuable opportunity to recognize the excellent work your team members/employees/co-workers/professors/students/section chapters have done over the year. Please take few moments to submit your nomination for any of these awards!. Please access the award nomination forms and guidelines from the section webpage at http://ewh.ieee.org/r6/phoenix/phxawdba_2006.html . You can also submit the nominations on-line by using the on-line submission button beneath the nomination form menu.

Please note that the deadline for submitting the nominations is December 9th. The recipients of the various awards will be recognized at the February 11th 2006 Phoenix Section Annual Banquet to be held at Airport Hilton.

If you have any additional questions, please contact Dr. Vasu Atluri, Awards Committee Chair, at (480) 554-0360 or by email at vpatluri@ieee.org.

Call for 2005 IEEE Phoenix Section Student Scholarships

Applications for the year 2005 IEEE Phoenix Section IEEE Student member scholarships are now requested. Every year the IEEE Phoenix section awards scholarships in varying amounts to qualified students from area universities and community colleges. For the year 2005, award guidelines, requirements and application form are now available for download from the Phoenix section webpage at <http://ewh.ieee.org/r6/phoenix/phxscho05.doc> . Please complete the forms and submit along with the supporting documentation to Prof. Keith Holbert of ASU at the address provided in the application packet on or before December 23rd, 2005. The recipients of the various awards will be recognized at the February 11th 2006 Phoenix Section Annual Banquet to be held at Airport Hilton.

Professors, please advise your students to make use of this valuable opportunity to apply for the scholarship. For any questions, please contact student activities faculty Prof. Keith Holbert at keith.holbert@asu.edu. Prof Holbert can be reached via phone at (480) 965-8594.

Best regards
Shamala Chickamenahalli
Chair, 2005 IEEE Phoenix Section

480-554-6774

Shamala.chickamenahalli@intel.com

IEEE Phoenix Section webpage <http://ewh.ieee.org/r6/phoenix/>

**January Meeting
Announcement for the
Phoenix Chapter of the
IEEE EMC Society**



Date: Wednesday, January 25th

Place: Embassy Suites Hotel

Address: 4400 South Rural Road, Tempe, Arizona

Address: Just South of U.S. 60 on West side of Rural Rd.

Time: 1:00PM - 7:00PM (12:45PM Registration)

Title: Tech Tour: Aerospace EMC, A Half-Day Technical Seminar with Demonstrations

The Phoenix Chapter of the IEEE EMC Society is pleased to host this event with leading industry experts including James Young of Rohde & Schwarz, Vince Rodriguez of ETS-Lindgren, and Harry Gaul of General Dynamics C4 Systems.

Program Outline

12:45 Registration

1:00 The Influence of Ground Plane Reflection on Antenna Calibration and Measurements by Harry Gaul, General Dynamics C4 Systems

This presentation will provide the theory and details of performing antenna calibrations in both free space and ground plane configurations in accordance with standards such as ANSI C63.5 and SAE ARP958. The concept of Normalized Site Attenuation (NSA) will be introduced as a means to derive the difference between free space and ground plane test configurations. Antenna range measurements will also be discussed from the standpoint of how to include the effects of reflection from earth with finite conductivity.

2:30 Break

2:45 Anechoic Chamber Solutions for Antenna Pattern Measurements by Vince Rodriguez, ETS-Lindgren

This presentation introduces the user to antenna ranges, and concentrates on rectangular and taper anechoic chambers for APM. Absorber technology, Quiet Zone levels, and far field requirements are discussed as well as the proper absorber treatment for both taper and rectangular chambers.

4:00 Break

4:15 Improving the Accuracy of EMI Measurements by James Young, Rohde & Schwarz

Topics to be addressed include: "The Spectrum Analyzer versus The EMI Receiver" (advantages and disadvantages), plus, the problems and benefits of using low noise amplifiers for increased sensitivity will be reviewed.

5:30-7:00 RECEPTION WITH THE SPEAKERS, HANDS ON DEMOS OF THE MATERIAL PRESENTED, RAFFLE FOR PRIZES!

About the Speakers:

Harry W. Gaul, P.E., is the EMC/TEMPEST Group Technical Manager for General Dynamics C4 Systems in Scottsdale, Arizona. He is a Registered Professional Engineer (PE) in the state of Arizona and is a NARTE Certified EMC Engineer. He is also the IEEE EMC Society Chapter Chair for the greater Phoenix area. Mr. Gaul has been involved in EMC, EMP, ESD and TEMPEST test and design engineering for more than 20 years. He received the B.S.M.E. degree from the University of Colorado in 1978 and the Technology M.B.A. degree from Arizona State University in 1998.

Vicente Rodríguez-Pereyra of ETS-Lindgren was born in Madrid, Spain. He obtained his BSEE from the University of Mississippi in 1994. He joined the department of EE at the University of Mississippi as a research assistant. He was involved in projects addressing the reduction of cross talk in high-speed digital circuits and the use of the Finite Difference Time Domain technique in antenna analysis. During this time he obtained the MS and Ph.D degrees in Engineering Science with an emphasis on Electromagnetic Theory in 1996 and 1999, respectively. In August 1999, Dr. Rodriguez joined the department of Electrical Engineering and Computer Science at Texas A&M University-Kingsville as a Visiting Assistant Professor. In June 2000, Dr. Rodriguez left the academic world and joined EMC Test Systems (now ETS-Lindgren) as an RF and Electromagnetics engineer. He is the author of more than 20 technical publications. Dr. Rodriguez is a member of the IEEE and several of its technical Societies including the MTT and the EMC Societies. He is also an active member of the Applied Computational Electromagnetic Society (ACES). Dr. Rodriguez is a full member of the Sigma Xi Scientific Research Society and of the Eta Kappa Nu Honor Society.

James Young is the sales and marketing manager for Rohde & Schwarz EMI products in the Americas. His engineering background includes system, circuit, ASIC and FPGA design for various communication products. He has also held product management and marketing positions with Cadence (Tality) in San Jose, CA, ParkerVision in Jacksonville FL, and Signal Space Design in Salt Lake City, UT. He holds a BSEET from Weber State University and an MBA from the University of Phoenix.

The Program Format:

The half-day will consist of a three part technical seminar. The goal of the seminar presentations is to provide practical information for the EMC engineer, designer or technician to actually use on the job! Following the technical seminar, a reception with the speakers will be held in a neighboring section of the hotel. Demonstrations of the material presented will be conducted. Participants can informally meet with the speakers and view these hands on demonstrations that are designed to “drive home” the material presented. Heavy appetizers will be served and two drink tickets per person will be provided for the open bar. (After that, the bar converts to a “cash bar” basis.) A door prize drawing will be held at the conclusion of the reception. Drop your business card in the bowl on the registration desk and enter to win the door prize. You must be present to win, of course!

There is no charge to attend this seminar, but a completed registration form must be on file in order to be admitted to the seminar. Seating is limited; seating will be reserved on a first come, first served basis. *NOTE: The speakers and program may be subject to change without prior notice.*

REGISTER ON LINE at www.techtoursite.com

Please visit our web site at <http://www.ewh.ieee.org/r6/phoenix/phoenixemc/index.html> for more information.

S A I N T 2 0 0 6 Call For Participation

The 2006 International Symposium on Applications and the Internet

January 23-27, 2006

Mesa, Arizona, USA

Co-sponsored by the IEEE Computer Society (IEEE-CS) and the
Information Processing Society of Japan (IPSJ)

<http://www.saintconference.org/> and <http://infonet.cse.kyutech.ac.jp/conf/saint06/>

The SAINT2006 Organizing Committee welcomes you all to Mesa, Arizona with 41 symposium paper presentations selected from 99 submitted papers, keynote speeches, 5 workshops on cutting-edge topics, 3 panel discussions, covering a diverse range of applications and their enabling Internet technologies.

Make your registration and hotel reservation as soon as possible

For your Registration and Hotel Reservation:

From SAINT Generic Page: <http://www.saintconference.org/>

> SAINT2006 Homepage > Go to Registration Page

Or

<http://infonet.cse.kyutech.ac.jp/conf/saint06/registration/index.html>

THEME: Pervasiveness and Diversity of the Internet

Over the past few years, the Internet has been revolutionizing the way we communicate by technical advances such as fiber optic networks, high-speed IP switching, DSL and CATV broadband accesses, along with the increasing performance of PCs, mobile terminals, etc. This growth has helped to identify the need for the Internet to support a diverse range of communications and to accommodate a wide variety of information, services, people, communities, and cultures. The Internet is also becoming to be ubiquitous and pervasive; accessible and usable from any device and through any network, including wireless and mobile. SAINT focuses on emerging and future Internet applications and their enabling technologies.

The symposium provides a forum for researchers and practitioners from the academic, industrial, public and governmental sectors, to share their latest innovations on Internet technologies and applications.

Areas of particular interest include:

Internet Agents
Collaboration Technology
Internet Content Management Systems
Content Delivery
E-business
Wireless and Mobile Internet
Standards for Internet Applications
GRID Computing

Internet Appliances
Novel Internet Applications
Internet Security
Network and Protocol Architecture
Internet Operation and Performance
Universal Accessibility
Other Internet Services

Keynotes:

(to be informed on the web soon)

Workshops:

SAINT2006 will feature workshops to provide forums for researchers and practitioners to share knowledge and exchange ideas on cutting-edge topics in Internet and applications. Papers selected by SAINT workshops will be published in a separate volume as an integral part of the SAINT2006 proceedings. There is only one registration fee for both the main conference and workshop participants who can attend any conference sessions.

The following 5 workshops are anticipated:

- 1: IPv6 Deployment of Technologies and Applications
- 2: Network Security Threats and Countermeasures
- 3: Next Generation Service Platforms for Future Mobile Systems (SPMS 2006)
- 4: Ubiquitous networking and enablers to context aware services
- 5: RFID and Extended Network; Deployment of Technologies and Applications

Panels:

(to be informed on the web soon)

Organizing Committee:**General Chairs:**

Shinji Shimojo, Osaka Univ., Japan
Joseph Urban, Arizona State Univ., USA

Program Chairs:

Patrick Bobbie, Southern Poly St Univ, USA
Haruo Takemura, Osaka Univ., Japan

Workshops Chairs:

Vijay Kumar, Univ. of Missouri-KC, USA
Hiroyuki Morikawa, Univ. of Tokyo, Japan

Panels Chairs:

Krzysztof Walczak, Poznan Univ. of Economics, Poland
Masayoshi Ohashi, KDDI, Japan

Publicity Chairs:

Ying Jin, Cal St Univ Sacramento, USA
Shigeru Miyake, Hitachi, Japan

Local Arrangements Chairs:

Hasan Davulcu, Arizona State University, USA
Jason Meltzer, meltmedia, USA

Registration Chairs:

Frank Tsui, Southern Polytechnic St Univ, USA
Koji Okamura, Kyushu Univ., Japan

Publication Chairs:

Huan Liu, Arizona State Univ., USA
Masato Tsuru, Kyushu Institute of Tech., Japan

Industry Liaison Chairs:

Ly Sauer, General Dynamics, USA
Susan Urban, Arizona State University, USA
Atsuhiko Goto, NTT, Japan

Financial Chairs:

Chung-Horng Lung, Carleton Univ., Canada
Kazutoshi Fujikawa, NAIST, Japan

Web Master:

Yutaka Nakamura, Kyushu Institute of Tech., Japan

Designated Technical Committee Chair:

Arun Iyengar, IBM Research, USA
Reiji Aibara, Hiroshima Univ., Japan

International Liaison Chairs:

Wojciech Cellary, Poznan Univ. of Economics, Poland
Yuji Matsumoto, NAIST, Japan

Awards Chairs:

Nian-Feng Tzeng, Univ of Louisiana-Lafayette, USA
James Kempf, DoCoMo Comm. Labs., USA

Steering Committee Chair:

Yuji Oie, Kyushu Institute of Tech., Japan

**ASU IEEE Student Branch
21st October 2005**



**Intel, Freescale, Raytheon, General Dynamics and SRP participate in
IEEE Student Industry at ASU Mixer**



In information age and technology based global economy, one must have the most productive and best educated workforce, and no investment yields as great a return as the investment in education. An educated and technically competent workforce is the foundation of every organization and the future of every economy.

In accordance with the above paradigm, ASU IEEE Student branch recently organized its semi annual 'ASU IEEE Industry-Student-Faculty Mixer' on the plush green lawns of Hayden library on October 21st, 2005 at Arizona State University, Tempe campus.

This is a semi annual event organized by the ASU IEEE Student branch and was attended by more than 100 highly motivated and enthusiastic students interacting with representatives from different companies such as Raytheon, Intel, Freescale to name a few, in an informal environment, inclusive with food and music.

The ASU IEEE Industry-Student-Faculty Mixer serves as a platform, not only for the industry representatives to interact with a small, focused group of students but also to inform and recruit the fresh and young talent pool, The event also serves the purpose of providing a venue for the companies to promote and enhance its general presence in the student body, in the form of corporate presentations during the week in which Mixer is organized. The ASU IEEE Student branch provided the venue, multimedia support, and advertising, allowing the company representatives to attract interested students for internships, part and full time positions.

The mixer also served as a platform for the faculty members such as Dr. Stephen Philips, Chair of Department of Electrical engineering, and Dr. Trevor Thornton, Director, Center for Solid State Electronics Research, to interact with graduate and undergraduate students outside formal setting and exchange information and discuss ideas.

In order to maintain a casual and informal environment for the mixer ASU IEEE branch also organized raffle and gave away raffle prizes to participating students.

Additionally, to maintain its presence among the students, ASU IEEE branch maintains a resume service, which allows the participating companies to search and recruit from a pool of highly qualified students. This service is a large database of IEEE student member's resumes, which are searchable by several criteria such as citizenship, GPA, and special interests.

IEEE Phoenix Section 2006 Annual Banquet

The IEEE Phoenix Section 2006 Annual Banquet is scheduled to be held on Saturday, February 11th, 2006, at Hilton Phoenix Airport located at 2435 South 47th Street, Phoenix, AZ - 85034, Phone: (480) 804-6017. The program includes:

6:00 pm – 7:00 pm	Registration and social hour
7:00 pm – 8:00 pm	Dinner
8:00 pm – 8:30 pm	Keynote speaker
8:30 pm – 9:30 pm	Awards

All IEEE members and their spouse all welcome. At the banquet, IEEE members of all grades, chapters / societies, corporations, student branches, and faculty are recognized. The awards are selected from the nominations. The organizing committee is seeking nominations for awards in all categories from IEEE Phoenix Section members. The nomination form can be obtained from IEEE Phoenix Section website located at <http://ewh.ieee.org/r6/phoenix/>. If you have any additional questions, contact Vasu Atluri, IEEE Phoenix Section Awards Committee Chair, at vpatluri@ieee.org.

IEEE Phoenix Area
Consultants Network



Consulting Projects with Today's Corporate Client
Mr. James Soudriette (The Galaxy Organization)

Date: Thursday, December 8, 2005

Time: Networking begins at 6:30 p.m.
Dinner begins at 7:00 p.m.

Place: Denny's Restaurant
3315 N. Scottsdale Rd.
Scottsdale, Arizona 85251

Abstract: The demographics of the corporate world have changed dramatically in the past decade. The changes bring a new personality to most of our client companies. Nowadays, client companies mandate new ways of approaching consulting projects. As a result, many consultants are re-engineering themselves to be more acceptable to today's younger (and more urgent) client base. This presentation will follow a short round-table discussion on items of interest to members and guests.

Speaker: Mr. James Soudriette is the Managing Director and Chairman of The Galaxy Organization. He has been working with officers and directors for more than 45 years in the American Southwest. His firm specializes in equity asset management, which includes real estate, patents, and licenses. He has founded the local chapter of many trade associations such as the Institute of Management Consultants, American Electronics Association, and American Marketing Association. Mr. Soudriette is also active in the Phoenix Rotary Club.

Directions: In Scottsdale, go west from Highway 101 and Indian School Road. Turn left on Scottsdale Road to head south. It is at the southeast corner on Scottsdale Road at Osborn Road.

Contacts: Vaughn Treude
IEEE PACN President
vaughn@nakota-software.com

Mike Jordan
IEEE PACN Program Chair
mike@colibresolutions.com

IEEE ANNOUNCEMENTS

All student branch/chapter officers/contacts and faculty advisors:

Officer info:

Prof Holbert, the section student branch advisor needs to have the new officer list that the section uses to update in the megaphone and also in the meeting announcement email distribution list. Please send the complete officer info for your branch/chapter to Prof Holbert.

Award and Scholarships:

Also you all must have received a recent email about the section award and scholarship applications. We would like to see increased number of applications for the scholarships and also good number of nominations for the awards. Please allocate few minutes now to attend to both the items.

Student activities update:

Earlier this year IEEE Phoenix section volunteers had been working with faculty advisors to get feedback on each of the student branch/chapters with a goal of increasing student participation at the IEEE section activities. Each of the volunteer will be in touch with you again this week or next. Please continue to provide your feedback on how it is working with your chapters. We would like to hear from you so we can help more.

Region 6 Virtual communities student activities portal:

The region 6 provides a virtual community webpage that is intended for all who are involved in Regional student activities, not just committee members. The student activities forum at the following URL for Student branch chairs/officers, section and area student activities chairs. You all will find it highly useful. Pl login and join with your IEEE account number. You receive an email **only** when there is an update at the regional level and very effective to remain **current** on regional/national level updates.

<https://www.ieeecommunities.org/region6sf>

Student paper and micro mouse contests:

Even though there is an area and region level student paper contest and micro mouse contest, phoenix section student representation has been minimum. Moving forward hope all of you make use of these opportunities to showcase your senior projects or any other projects at the section/region levels.

Students: Best of luck with those fast approaching exams!

Best regards
Shamala Chickamenahalli
2005 Chair, IEEE Phoenix Section
Staff Packaging Engineer
Intel Corporation
Chandler AZ-85226